

SMD Power Inductor

TMPA606010SP-Series(N)-D

1. Features

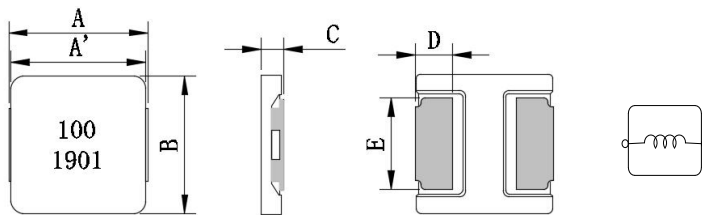
1. Shielded construction.
2. Capable of corresponding high frequency .
3. Low loss realized with low DCR.
4. High performance (Isat) realized by metal dust core.
5. Ultra low buzz noise, due to composite construction.
6. 100% Lead(Pb)-Free and RoHS compliant.
7. Operating temperature -40~+125°C(Including self - temperature rise)



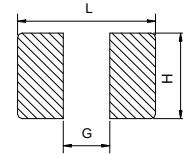
2. Applications

Note PC power system · incl. IMVP-6
DC/DC converter .

3. Dimensions



Recommend PC Board Pattern

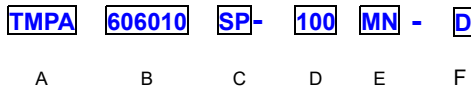


Series	A(mm)	A'(mm)	B(mm)	C(mm)	D(mm)	E(mm)
TMPA606010SP	6.1±0.3	6.0±0.2	6.1±0.3	0.8±0.2	1.75±0.3	4.0±0.2

L(mm)	G(mm)	H(mm)
7.0	2.8	4.5

Note: 1. The above PCB layout reference only.
2. Recommend solder paste thickness at 0.12mm and above.

4. Part Numbering



- A: Series
- B: Dimension BxC
- C: Type Standard.
- D: Inductance 100=10.0uH
- E: Inductance Tolerance M=±20%
- F: Code Marking: Black.100and 1901(19 YY, 01 WW, follow production date).

5. Specification

Part Number	Inductance L0 (uH) ±20%	I rms (A)	I sat (A)	DCR (mΩ)Typ	DCR (mΩ)Max
TMPA606010SP-6R8MN-D	6.80	2.1	2.5	164	197
TMPA606010SP-100MN-D	10.0	1.7	2.1	259	310

Note:

1. Test frequency : Ls : 100KHz /1.0V.
2. All test data referenced to 25°C ambient.
3. Testing Instrument(or equ) : L: HP4284A,CH11025,CH3302,CH1320,CH1320S LCR METER / Rdc:CH16502,Agilent33420A MICRO OHMMETER.
4. Heat Rated Current (Irms) will cause the coil temperature rise approximately ΔT of 40°C
5. Saturation Current (Isat) will cause L0 to drop approximately 30%.
6. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions.Circuit design,component,PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
7. Special inquiries besides the above common used types can be met on your requirement.

6. Typical Performance Curves

